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WEI(10) **Pub. No.: US 2022/0386505 A1**(43) **Pub. Date: Dec. 1, 2022**(54) **HEAT DISSIPATION SUBRACK, HEAT
DISSIPATION CABINET, AND BACKPLANE
COMMUNICATION SYSTEM**(71) Applicant: **ZTE CORPORATION**, Shenzhen,
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ABSTRACT

Disclosed is a heat dissipation subrack, including a cabinet body defining an accommodating space. The cabinet body defines an air inlet, two air supplementing openings, and an air outlet. The accommodating space has an air inlet region, and a heat source region communicatively coupled to the air inlet region. An opening direction of the air inlet and an opening direction of each of the air supplementing openings intersect in the air inlet region. The cabinet body includes multiple baffles, each of the baffles includes two wind shielding surfaces, and airflow passages are defined between each two adjacent baffles and between one of inner walls of the cabinet body and a baffle adjacent to the one of the inner walls of the cabinet body.

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